

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0739447017

Status:

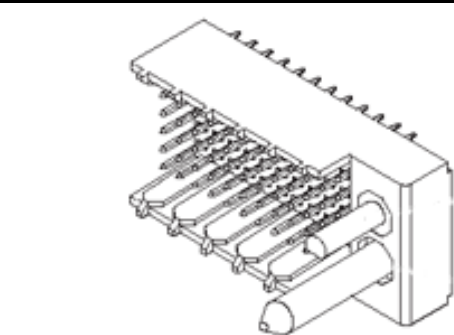
Active

Overview:

HDM Backplane Connector System

Description:

HDM Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, Guide Post Location A, Polarizing Key Position N/A, 144 Circuits



Series image - Reference only

Documents:

3D Model

Packaging Specification PK-70873-0818 (PDF)

Drawing (PDF)

RoHS Certificate of Compliance (PDF)

Product Specification PS-73670-9999 (PDF)

Agency Certification	
CSA	LR19980
UL	E29179
General	
Product Family	Backplane Connectors
Series	73944
Application	Backplane
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800755031096
Physical	
Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	Yes
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	8.594/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	Yes
PCB Retention	None
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Polarized to PCB	No
Stackable	No
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole

EU ELV	
Not Relevant	
EU RoHS	China RoHS
Compliant	
REACH SVHC	
Not Contained Per - ED/71/2019 (16 July 2019)	
Halogen-Free	
Status	
Low-Halogen	
For more information, please visit Contact US	
China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series

73944 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling FAQ	
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.	
Global	
Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Backplane Insertion	622005703
Head for 144 Circuits	

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	040
Lead-freeProcess Capability	SMC&WAVE
Max. Cycles at Max. Process Temperature	003
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Product Specification	PS-73670-9999
Sales Drawing	SD-73944-001

This document was generated on 09/15/2019

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Molex:

73944-7017